

**HEXFET® Power MOSFET for DC-DC Converters**

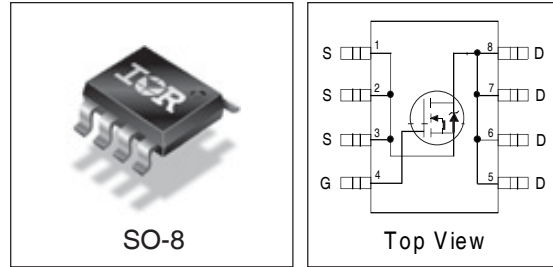
- N-Channel Application-Specific MOSFETs
- Ideal for CPU Core DC-DC Converters
- Low Conduction Losses
- Low Switching Losses
- 100% Tested for R<sub>g</sub>
- Lead-Free

**Description**

This new device employs advanced HEXFET Power MOSFET technology to achieve an unprecedented balance of on-resistance and gate charge. The reduced conduction and switching losses make it ideal for high efficiency DC-DC converters that power the latest generation of microprocessors.

The IRF7811WPbF has been optimized for all parameters that are critical in synchronous buck converters including R<sub>DS(on)</sub>, gate charge and Cdv/dt-induced turn-on immunity. The IRF7811WPbF offers particularly low R<sub>DS(on)</sub> and high Cdv/dt immunity for synchronous FET applications.

The package is designed for vapor phase, infra-red, convection, or wave soldering techniques. Power dissipation of greater than 3W is possible in a typical PCB mount application.



**DEVICE CHARACTERISTICS<sup>⑤</sup>**

IRF7811WPbF	
R <sub>DS(on)</sub>	9.0mΩ
Q <sub>G</sub>	22nC
Q <sub>sw</sub>	10.1nC
Q <sub>oss</sub>	12nC

**Absolute Maximum Ratings**

Parameter	Symbol	IRF7811WPbF	Units
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±12	
Continuous Drain or Source Current (V <sub>GS</sub> ≥ 4.5V)	T <sub>A</sub> = 25°C	I <sub>D</sub>	14
	T <sub>L</sub> = 90°C		13
Pulsed Drain Current <sup>①</sup>	I <sub>DM</sub>	109	A
Power Dissipation	T <sub>A</sub> = 25°C	P <sub>D</sub>	3.1
	T <sub>L</sub> = 90°C		3.0
Junction & Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C
Continuous Source Current (Body Diode)	I <sub>S</sub>	3.8	A
Pulsed Source Current <sup>①</sup>	I <sub>SM</sub>	109	

**Thermal Resistance**

Parameter		Max.	Units
Maximum Junction-to-Ambient <sup>③</sup>	R <sub>θJA</sub>	40	°C/W
Maximum Junction-to-Lead	R <sub>θJL</sub>	20	°C/W

# IRF7811WPbF

International  
 Rectifier

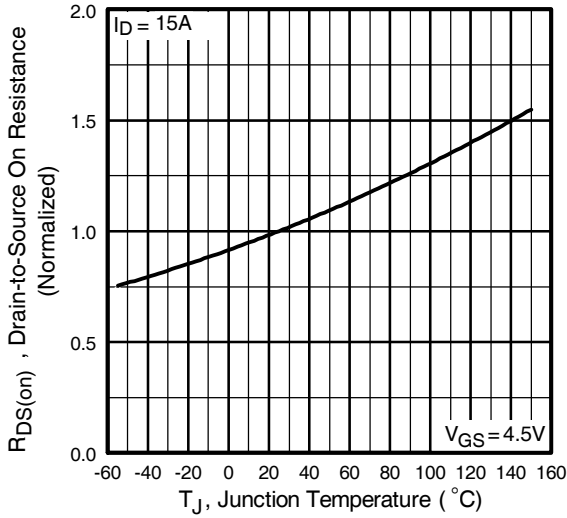
## Electrical Characteristics

Parameter		Min	Typ	Max	Units	Conditions
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Static Drain-Source on Resistance	$R_{DS(on)}$		9.0	12	m $\Omega$	$V_{GS} = 4.5V, I_D = 15A$ ②
Gate Threshold Voltage	$V_{GS(th)}$	1.0			V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Drain-Source Leakage Current	$I_{DSS}$			30	$\mu A$	$V_{DS} = 24V, V_{GS} = 0$
				150		$V_{DS} = 24V, V_{GS} = 0,$ $T_j = 100^\circ C$
Gate-Source Leakage Current	$I_{GSS}$			$\pm 100$	nA	$V_{GS} = \pm 12V$
Total Gate Chg Cont FET	$Q_G$		22	33	nC	$V_{GS}=5.0V, I_D=15A, V_{DS}=16V$
Total Gate Chg Sync FET	$Q_G$		16.3			$V_{GS} = 5V, V_{DS} < 100mV$
Pre-Vth Gate-Source Charge	$Q_{GS1}$		3.5			$V_{DS} = 16V, I_D = 15A, V_{GS} = 5.0V$
Post-Vth Gate-Source Charge	$Q_{GS2}$		1.2			
Gate to Drain Charge	$Q_{GD}$		8.8			
Switch Chg( $Q_{GS2} + Q_{gd}$ )	$Q_{sw}$		10.1			
Output Charge	$Q_{OSS}$		12			$V_{DS} = 16V, V_{GS} = 0$
Gate Resistance	$R_G$		2.0	4.0	$\Omega$	
Turn-on Delay Time	$t_{d(on)}$		11		ns	$V_{DD} = 16V, I_D = 15A$ $V_{GS} = 5.0V$ Clamped Inductive Load
Rise Time	$t_r$		11			
Turn-off Delay Time	$t_{d(off)}$		29			
Fall Time	$t_f$		9.9			
Input Capacitance	$C_{iss}$	-	2335	-	pF	$V_{DS} = 16V, V_{GS} = 0$
Output Capacitance	$C_{oss}$	-	400	-		
Reverse Transfer Capacitance	$C_{rss}$	-	119	-		

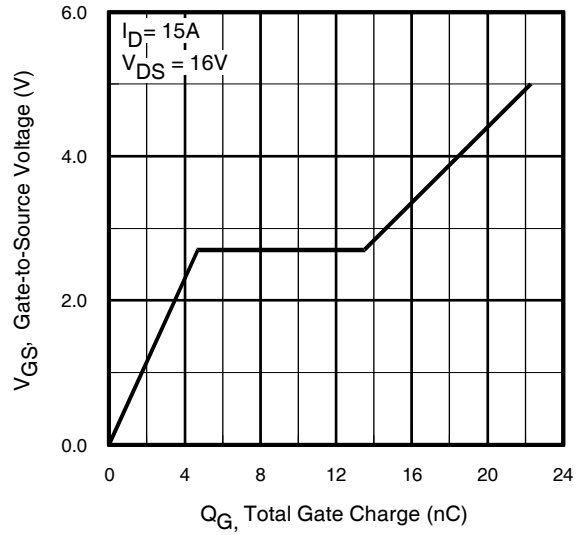
## Source-Drain Rating & Characteristics

Parameter		Min	Typ	Max	Units	Conditions
Diode Forward Voltage*	$V_{SD}$			1.25	V	$I_S = 15A$ ②, $V_{GS} = 0V$
Reverse Recovery Charge④	$Q_{rr}$		45		nC	$di/dt \sim 700A/\mu s$ $V_{DS} = 16V, V_{GS} = 0V, I_S = 15A$
Reverse Recovery Charge (with Parallel Schottky)④	$Q_{rr(s)}$		41		nC	$di/dt = 700A/\mu s$ (with 10BQ040) $V_{DS} = 16V, V_{GS} = 0V, I_S = 15A$

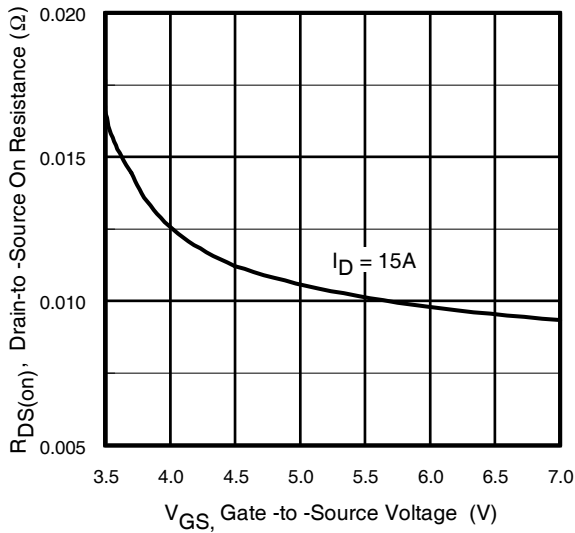
- Notes:**
- ① Repetitive rating; pulse width limited by max. junction temperature.
  - ② Pulse width  $\leq 400 \mu s$ ; duty cycle  $\leq 2\%$ .
  - ③ When mounted on 1 inch square copper board
  - ④ Typ = measured -  $Q_{oss}$
  - ⑤ Typical values of  $R_{DS(on)}$  measured at  $V_{GS} = 4.5V$ ,  $Q_G$ ,  $Q_{sw}$  and  $Q_{OSS}$  measured at  $V_{GS} = 5.0V, I_F = 15A$ .



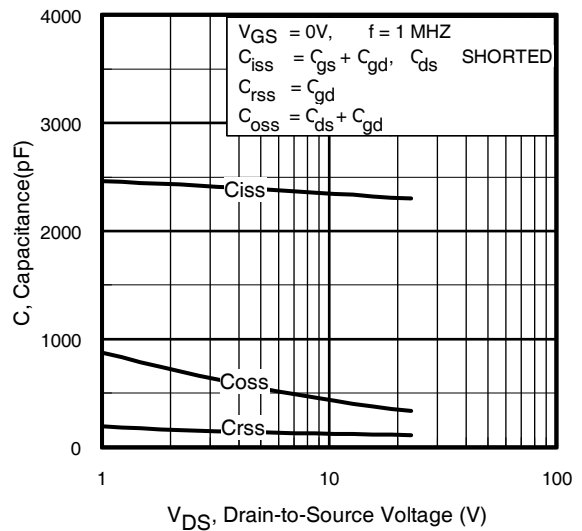
**Fig 1.** Normalized On-Resistance Vs. Temperature



**Fig 2.** Typical Gate Charge Vs. Gate-to-Source Voltage



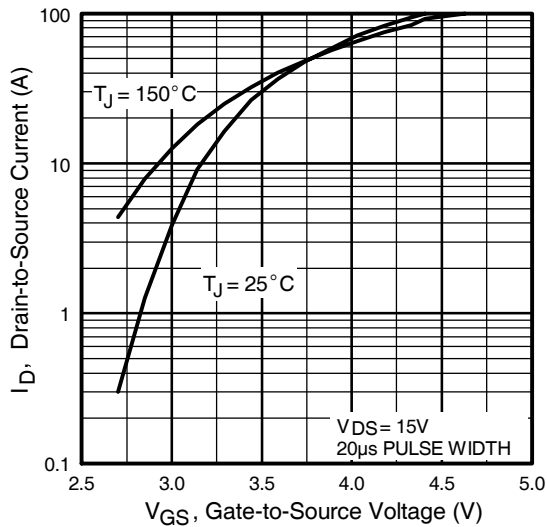
**Fig 3.** On-Resistance Vs. Gate Voltage



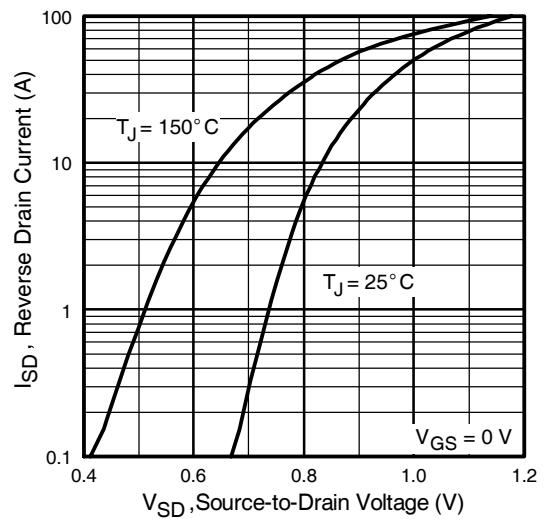
**Fig 4.** Typical Capacitance Vs. Drain-to-Source Voltage

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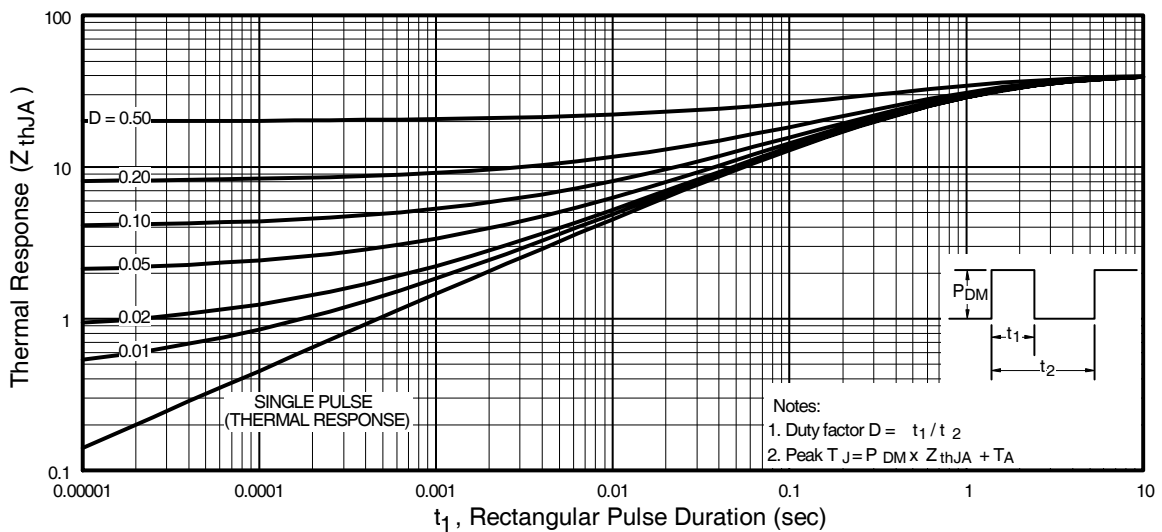
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**Fig 5.** Typical Transfer Characteristics



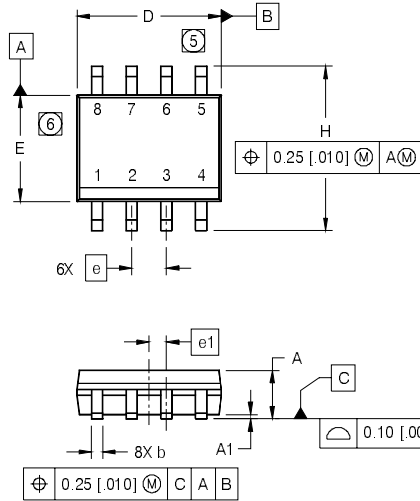
**Fig 6.** Typical Source-Drain Diode Forward Voltage



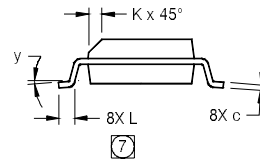
**Figure 7.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

## SO-8 Package Outline (Mosfet & Fetky)

Dimensions are shown in millimeters (inches)



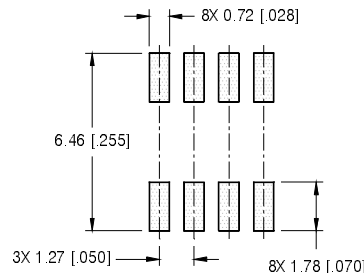
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



**NOTES:**

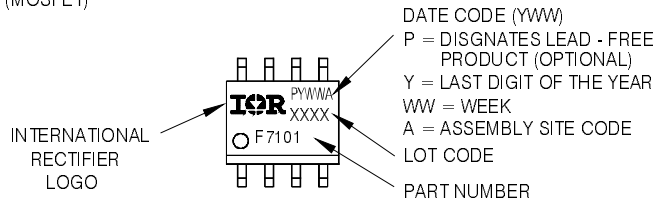
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-01 2AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [0.006].
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [0.010].
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

**FOOTPRINT**



## SO-8 Part Marking Information

EXAMPLE: THIS IS AN IRF7101 (MOSFET)



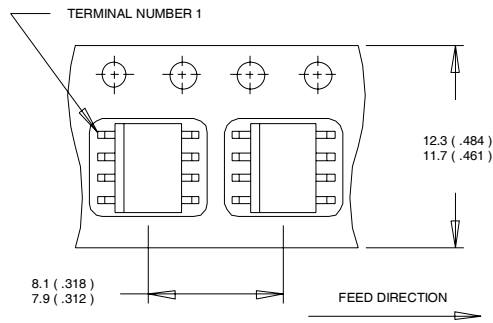
**Note:** For the most current drawing please refer to IR website at: <http://www.irf.com/package/>  
[www.irf.com](http://www.irf.com)

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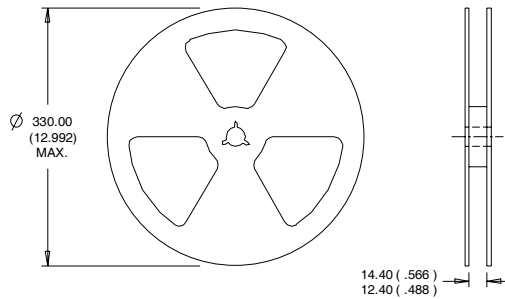
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## SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

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Data and specifications subject to change without notice.  
This product has been designed and qualified for the Consumer market.  
Qualification Standards can be found on IR's Web site.

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**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
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